



Material Content Data Sheet



Halogen-Free

Sales Product Name	BC 858BW H6327	Issued	01. May 2021
MA#	MA000845534		
Package	PG-SOT323-3-1	Weight*	5.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000			8	
	noble metal	gold	7440-57-5	0.005	0.08		769	
	inorganic material	silicon	7440-21-3	0.039	0.66	0.74	6569	7346
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1323	
	non noble metal	copper	7440-50-8	2.617	43.90	44.08	439176	441028
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	853	853
encapsulation	organic material	carbon black	1333-86-4	0.031	0.53		5268	
	plastics	epoxy resin	-	0.675	11.33		113267	
	inorganic material	silicondioxide	60676-86-0	2.433	40.83	52.69	408288	526823
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22270	22270
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1680	1680
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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